

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A dielectric paste ~~containing comprising~~ ethyl cellulose having an apparent weight average molecular weight of 110,000 to 190,000 as a binder and at least one kind of solvent selected from the group consisting of isobornyl acetate, ~~dihydroterpinal methyl ether, terpinal methyl ether, α-terpinal~~ acetate, I-dihydrocarvyl acetate, I-menthyl acetate, I-menthone, I-perillyl acetate and I-carvyl acetate.

2. (Original) A dielectric paste adapted for forming a spacer layer in accordance with Claim 1, wherein ethyl cellulose having an apparent weight average molecular weight of 115,000 to 180,000 is contained as a binder.

3. (Currently Amended) A method for fabricating a multi-layered unit for a multi-layered ceramic electronic component comprising a step of printing a dielectric paste ~~containing including~~ ethyl cellulose having an apparent weight average molecular weight of 110,000 to 190,000 as a binder and at least one kind of solvent selected from the group consisting of isobornyl acetate, ~~dihydroterpinal methyl ether, terpinal methyl ether, α-terpinal~~ acetate, I-dihydrocarvyl acetate, I-menthyl acetate, I-menthone, I-perillyl acetate and I-carvyl acetate on a ceramic green sheet containing a butyral system resin as a binder in a predetermined pattern, thereby forming a spacer layer.

4. (Original) A method for fabricating a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 3, wherein the dielectric paste contains ethyl cellulose having an apparent weight average molecular weight of 115,000 to 180,000 is contained as a binder.

5. (Previously Presented) A method for fabricating a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 3, wherein the degree of polymerization of a butyral system resin is equal to or larger than 1000.

6. (Previously Presented) A method for fabricating a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 5, wherein the degree of butyralization of butyral system resin is equal to or larger than 64 mol % and equal to or smaller than 78 mol %.